

Intel[®] 5000 Series Chipset Memory Controller Hub (MCH) for Embedded Applications

Thermal and Mechanical Design Guidelines

September 2006



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Revision History

Date	Revision	Description
September 2006	001	Initial public release.



1.0 Introduction

As the complexity of computer systems increases, so do the power dissipation requirements. Care must be taken to ensure that the additional power is properly dissipated. Typical methods to improve heat dissipation include selective use of ducting, and/or passive heatsinks.

The goals of this document are to:

- Outline the thermal and mechanical operating limits and specifications for the Intel® 5000 Series Chipset MCH.
- Describe reference thermal solutions that meet the specification of the Intel® 5000 Series Chipset MCH in Embedded Applications.

Properly designed thermal solutions provide adequate cooling to maintain the Intel® 5000 Series Chipset MCH die temperatures at or below thermal specifications. This is accomplished by providing a low local-ambient temperature, ensuring adequate local airflow, and minimizing the die to local-ambient thermal resistance. By maintaining the Intel® 5000 Series Chipset MCH die temperature at or below the specified limits, a system designer can ensure the proper functionality, performance, and reliability of the chipset. Operation outside the functional limits can degrade system performance and may cause permanent changes in the operating characteristics of the component.

The simplest and most cost-effective method to improve the inherent system cooling characteristics is through careful chassis design and placement of fans, vents, and ducts. When additional cooling is required, component thermal solutions may be implemented in conjunction with system thermal solutions. The size of the fan or heatsink can be varied to balance size and space constraints with acoustic noise.

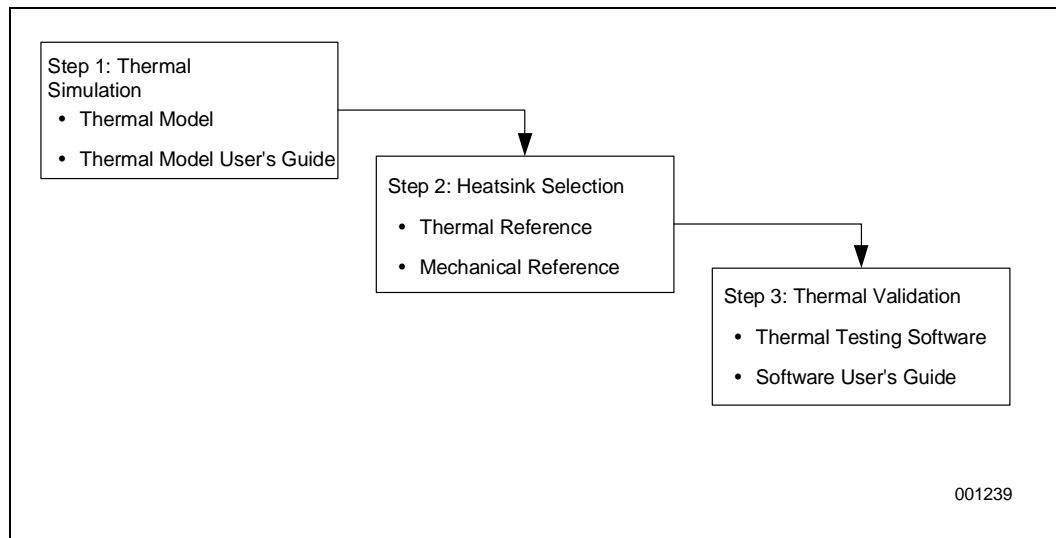
This document addresses thermal design and specifications for the Intel 5000 Series chipset MCH components only. For thermal design information on other chipset components, refer to the respective component datasheet. For the PXH, refer to the *Intel® 6700PXH 64-bit PCI Hub Thermal/Mechanical Design Guidelines*. For the Intel® 631xESB/632xESB I/O Controller Hub, refer to the *Intel® 631xESB/632xESB I/O Controller Hub Thermal/Mechanical Design Guidelines*.

Note: Unless otherwise specified, the term “MCH” refers to the Intel® 5000 Series Chipset MCH.

1.1 Design Flow

To develop a reliable, cost-effective thermal solution, several tools have been provided to the system designer. [Figure 1](#) illustrates the design process implicit to this document and the tools appropriate for each step.

Figure 1. Thermal Design Process





1.2 Definition of Terms

Table 1.

BGA	Ball grid array. A package type, defined by a resin-fiber substrate, onto which a die is mounted, bonded and encapsulated in molding compound. The primary electrical interface is an array of solder balls attached to the substrate opposite the die and molding compound.
BLT	Bond line thickness. Final settled thickness of the thermal interface material after installation of heatsink.
Intel® 631xESB/632xESB I/O Controller Hub	The chipset component that integrates an Ultra ATA 100 controller, six Serial ATA host controller ports, one EHCI host controller, and four UHCI host controllers supporting eight external USB 2.0 ports, LPC interface controller, flash BIOS interface controller, PCI interface controller, Azalia / AC'97 digital controller, integrated LAN controller, an ASF controller and a ESI for communication with the MCH. The Intel 631xESB/632xESB I/O Controller Hub component provides the data buffering and interface arbitration required to ensure that system interfaces operate efficiently and provide the bandwidth necessary to enable the system to obtain peak performance.
Intel® E7500 series	Server class chipsets with support for DDR and DDR2 memory interfaces with high speed I/O support for 64 bit PCI and PCI express.
MCH	Memory controller hub. The chipset component that contains the processor interface, the memory interface, the PCI Express* interface and the ESI interface.
PXH	Intel® 6700PXH 64-bit Hub. The chipset component that performs PCI bridging functions between the PCI Express interface and the PCI Bus. It contains two PCI bus interfaces that can be independently configured to operate in PCI (33 or 66 MHz) or PCI-X* mode 1 (66, 100 or 133 MHz), for either 32 or 64 bit PCI devices.
PXH-V	Intel® 6702PXH 64-bit Hub. The chipset component that performs PCI bridging functions between the PCI Express interface and the PCI Bus. It contains one PCI bus interface that can be configured to operate in PCI (33 or 66MHz) or PCI-X mode 1 (66, 100 or 133 MHz).
T _{case_max}	Maximum IHS temperature allowed. This temperature is measured at the geometric center of the top of the IHS.
T _{case_min}	Minimum IHS temperature allowed. This temperature is measured at the geometric center of the top of the IHS.
TDP	Thermal design power. Thermal solutions should be designed to dissipate this target power level. TDP is not the maximum power that the chipset can dissipate.

1.3 Reference Documents

The reader of this specification should also be familiar with material and concepts presented in the following documents:

Table 2. Reference Documents

Title	Location
Intel®6700PXH 64-bit PCI Hub Thermal/Mechanical Design Guidelines	http://www.intel.com/design/chipsets/designex/302817.htm
Intel® 6700PXH 64-bit PCI Hub Datasheet	http://www.intel.com/design/chipsets/datashts/302628.htm
Intel® 631xESB / 632xESB I/O Controller Hub Datasheet	http://www.intel.com/design/chipsets/datashts/313082.htm
Intel® 631xESB/632xESB I/O Controller Hub Thermal/Mechanical Design Guidel	http://www.intel.com/design/chipsets/designex/313073.htm

**Table 2. Reference Documents**

Title	Location
Intel® 5000P/5000V/5000Z Chipset Memory Controller Hub (MCH) External Design Guide	Reference #21476, see Note.
Intel® 5000X Chipset Memory Controller Hub (MCH) External Design Guide	Reference #21477, see Note.
Dual-Core Intel® Xeon® Processor 5000 Series Datasheet	http://www.intel.com/design/xeon/datashts/313079.htm
Dual-Core Intel® Xeon® Processor 5000 Series Thermal/Mechanical Design Guidelines	http://www.intel.com/design/chipsets/designex/313067.htm
BGA/OLGA Assembly Development Guide	See Note.
Various system thermal design suggestions	http://www.formfactors.org

Note: These documents are available through your Intel field sales representative. Some documents may not be available at this time.



2.0 Packaging Technology

The Intel® 5000 Series Chipset consists of three individual components: the Memory Controller Hub (MCH), the Intel® 6700PXH 64-bit PCI Hub (PXH) and the Intel® 631xESB/632xESB I/O Controller Hub. Intel 5000 Series chipset MCH components use a 42.5 mm, 10-layer flip chip ball grid array (FC-BGA) package (see [Figure 2](#), [Figure 3](#), and [Figure 4](#)). For information on the PXH package, refer to the *Intel® 6700PXH 64-bit PCI Hub Thermal/Mechanical Design Guidelines*. For information on the Intel® 631xESB/632xESB I/O Controller Hub package, refer to the *Intel® 631xESB/632xESB I/O Controller Hub Thermal/Mechanical Design Guidelines*.

Figure 2. MCH Package Dimensions (Top View)

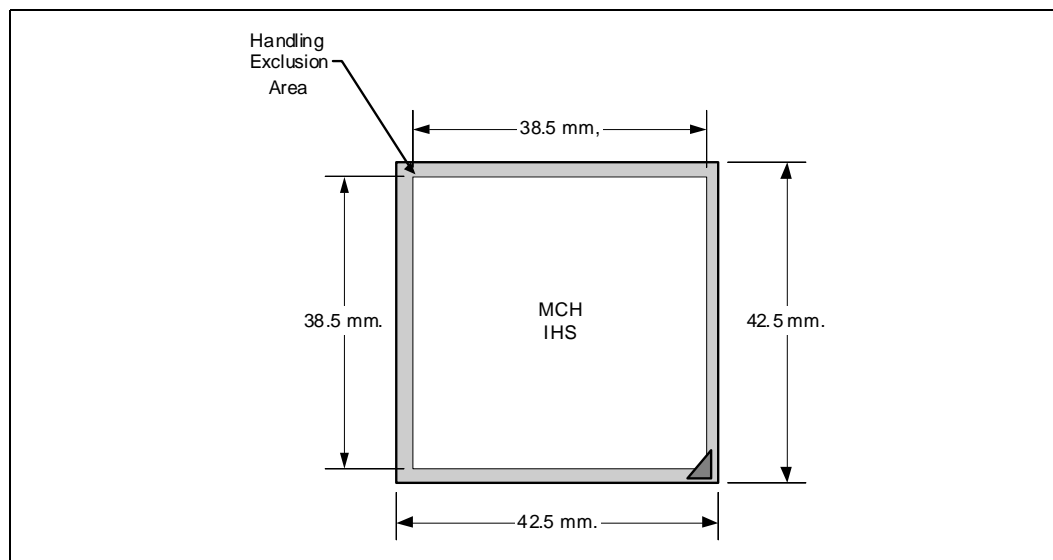
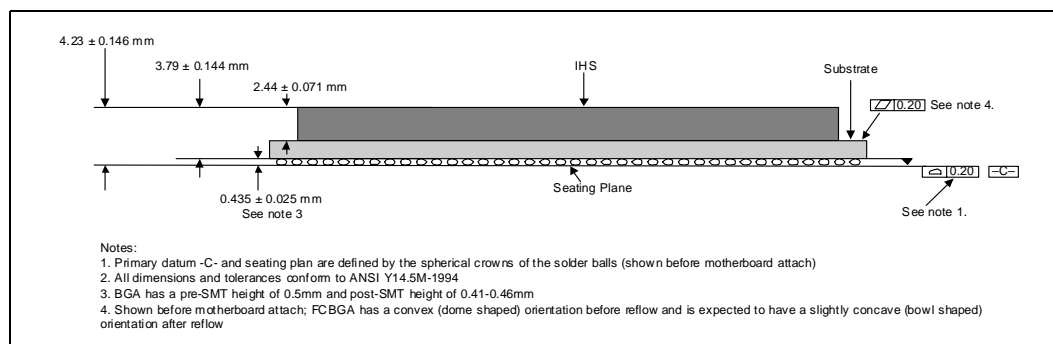


Figure 3. MCH Package Dimensions (Side View)



[illegible]

1. All dimensions are in millimeters.
2. All dimensions and tolerances conform to ANSI Y14.5M-1994.

The Intel® 5000 Series Chipset MCH package has an integrated heat spreader (IHS) that is capable of sustaining a maximum static normal load of 15 lbf. These mechanical load limits must not be exceeded during heatsink installation, mechanical stress testing, standard shipping conditions and/or any other use condition.

1. The heatsink attach solutions must not include continuous stress to the chipset package with the exception of a uniform load to maintain the heatsink-to-package thermal interface.
2. These specifications apply to uniform compressive loading in a direction perpendicular to the IHS top surface.

These specifications are based on limited testing for design characterization. Loading limits are for the package only.



3.0 Thermal Specifications

3.1 Thermal Design Power (TDP)

Analysis indicates that real applications are unlikely to cause the MCH component to consume maximum power dissipation for sustained time periods. Therefore, in order to arrive at a more realistic power level for thermal design purposes, Intel characterizes power consumption based on known platform benchmark applications. The resulting power consumption is referred to as the Thermal Design Power (TDP). TDP is the target power level to which the thermal solutions should be designed. TDP is not the maximum power that the chipset can dissipate.

For TDP specifications, see [Table 3](#) for the Intel® 5000 Series Chipset MCH. FC-BGA packages have poor heat transfer capability into the board and have minimal thermal capability without thermal solution. Intel recommends that system designers plan for a heatsink when using Intel® 5000 series.

3.2 Case Temperature

To ensure proper operation and reliability of the Intel® 5000 Series Chipset MCH, the case temperatures must be at or between the maximum/minimum operating temperature ranges as specified in [Table 3](#). System and/or component level thermal solutions are required to maintain these temperature specifications. Refer to [Section 5.0, “Thermal Metrology” on page 15](#) for guidelines on accurately measuring package case temperatures.

Table 3. Intel® 5000 Series Chipset MCH Thermal Specifications

Parameter	Value	Notes
T _{case_max}	105°C	
T _{case_min}	5°C	
TDP _{with 1 active memory channel}	24.7 W	
TDP _{with 2 active memory channel}	26.4 W	
TDP _{with 4 active memory channel}	30.0 W	

Note: These specifications are based on preliminary silicon characterization; however, they may be updated as further data becomes available.



4.0 Thermal Simulation

Intel provides thermal simulation models of the Intel® 5000 Series Chipset MCH and associated user's guides to aid system designers in simulating, analyzing, and optimizing their thermal solutions in an integrated, system-level environment. The models are for use with the commercially available Computational Fluid Dynamics (CFD)-based thermal analysis tool FLOTHERM* (version 5.1 or higher) by Flomerics, Inc. Contact your Intel field sales representative to order the thermal models and user's guides.



5.0 Thermal Metrology

The system designer must make temperature measurements to accurately determine the thermal performance of the system. Intel has established guidelines for proper techniques to measure the MCH case temperatures. [Section 5.1](#) provides guidelines on how to accurately measure the MCH case temperatures. [Section 5.2](#) contains information on running an application program that will emulate anticipated maximum thermal design power ([Figure 5](#)).

5.1 MCH Case Measurement

Intel® 5000 Series Chipset MCH cooling performance is determined by measuring the case temperature using a thermocouple. For case temperature measurements, the attached method outlined in this section is recommended for mounting a thermocouple.

Special care is required when measuring case temperature (T_C) to ensure an accurate temperature measurement. Thermocouples are often used to measure T_C . When measuring the temperature of a surface that is at a different temperature from the surrounding local ambient air, errors may be introduced in the measurements. The measurement errors can be caused by poor thermal contact between the thermocouple junction and the surface of the integrated heat spreader, heat loss by radiation, convection, by conduction through thermocouple leads, or by contact between the thermocouple cement and the heatsink base. To minimize these measurement errors, the approach outlined in the next section is recommended.

5.1.1 Supporting Test Equipment

To apply the reference thermocouple attach procedure, it is recommended that you use the equipment (or equivalent) given in [Figure 4](#).

**Table 4. Thermocouple Attach Support Equipment**

Item	Description	Part number
Measurement and Output		
Microscope	Olympus Light microscope or equivalent	SZ-40
Digital Multimeter	Digital Multimeter for resistance measurement	Not Available
Test Fixture(s)		
Micromanipulator* (See note)	Micromanipulator set from YOU Ltd. or equivalent Mechanical 3D arm with needle (not included) to maintain TC bead location during the attach process.	YOU-3
Miscellaneous Hardware		
Super Bonder* 498 Thermal Cycling Resistant Instant Adhesive	Super glue w/thermal characteristics	49850
Adhesive Accelerator	Loctite 7452* for fast glue curing	18490
Kapton Tape	For holding thermocouple in place or equivalent	Not Available
Thermocouple	Omega, 36 gauge, "T" Type	5SRTC-TT-36-72
Calibration and Control		
Ice Point* Cell	Omega, stable 0°C temperature source for calibration and offset	TRCIII
Hot Point* Cell	Omega, temperature source to control and understand meter slope gain	CL950-A-110

Note: Three axes set consists of (1ea. U-31CF), (1ea. UX-6-6), (1ea. USM6) and (1ea. UPN-1). More information available at: http://www.narishige.co.jp/you_ltd/english/products/set/you-set.htm#3

5.1.2 Thermal Calibration and Controls

It is recommended that full and routine calibration of temperature measurement equipment be performed before attempting to perform temperature case measurement of the Intel® 5000 Series Chipset MCH. Intel recommends checking the meter probe set against known standards. This should be done at 0°C (using ice bath or other stable temperature source) and at an elevated temperature, around 80°C (using an appropriate temperature source).

Wire gauge and length also should be considered as some less expensive measurement systems are heavily impacted by impedance. There are numerous resources available throughout the industry to assist with implementation of proper controls for thermal measurements.

Notes:

1. It is recommended to follow company standard procedures and wear safety items like glasses for cutting the IHS and gloves for chemical handling.
2. Ask your Intel field sales representative if you need assistance to groove and/or install a thermocouple according to the reference process.

5.1.3 IHS Groove

Cut a groove in the package IHS according to the drawing given in [Figure 6](#).



Figure 5. IHS Groove Dimensions

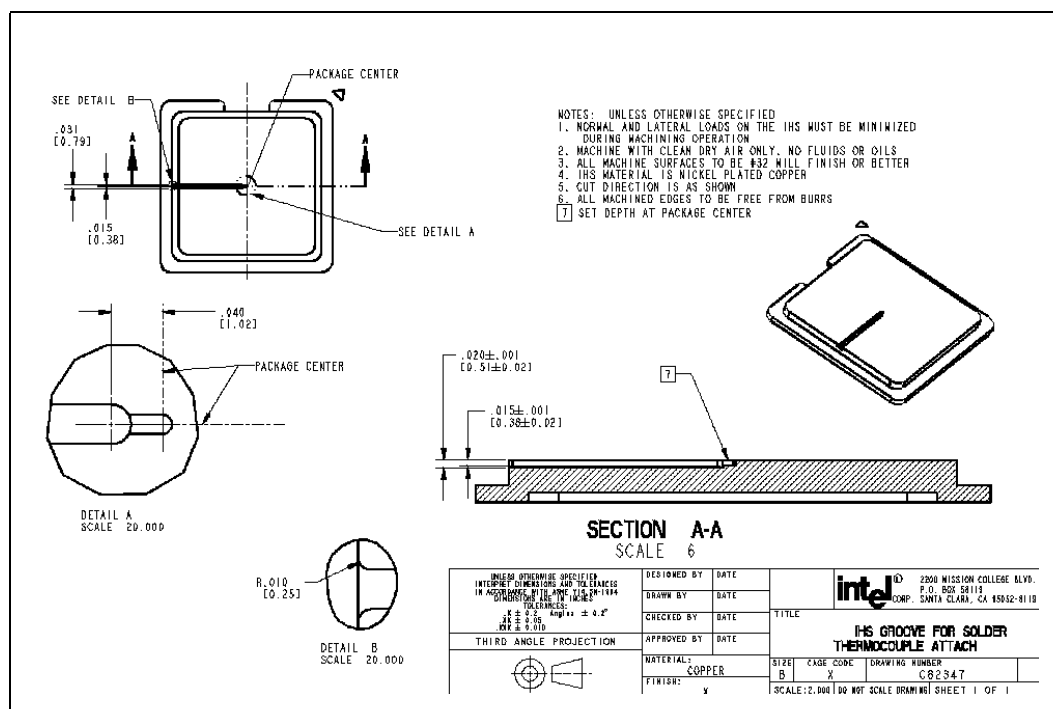
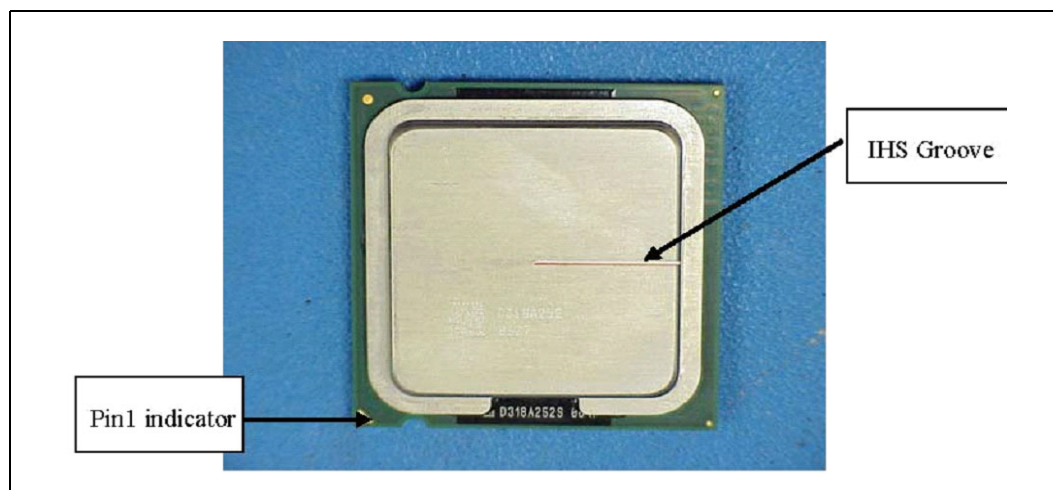


Figure 6. Orientation of Thermocouple Groove Relative to Package Pin

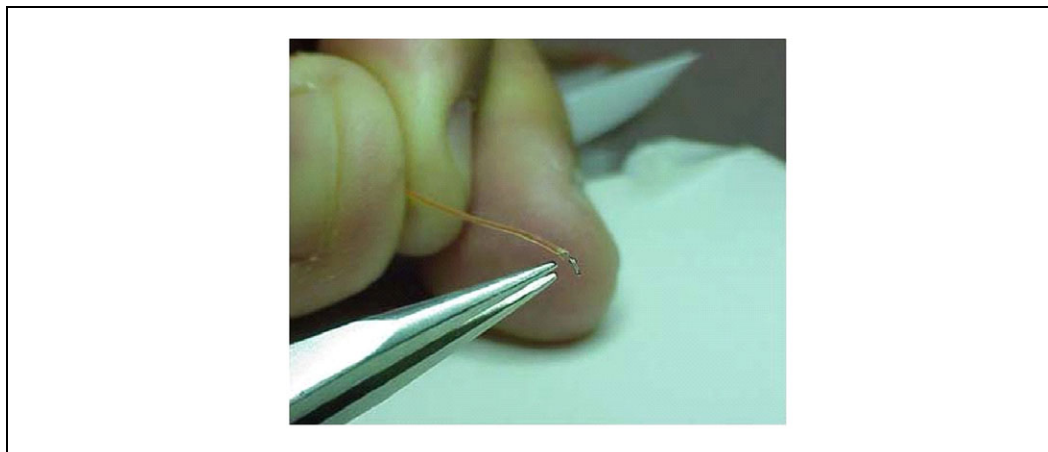


5.1.4 Thermocouple Conditioning and Preparation

1. Use a calibrated thermocouple as specified in Table 4.
2. Measure the thermocouple resistance by holding both wires on one probe and the tip of thermocouple to the other probe of the DMM (compare to thermocouple resistance specifications).
3. Straighten the wire for about 38 mm (1½ inch) from the bead to place it inside the channel.

4. Bend the tip of the thermocouple to approximately a 45 degree angle by 0.8 mm (0.030 inch) from the tip ([Figure 7](#)).

Figure 7. Bending the Tip of the Thermocouple



5.1.5 Thermocouple Attachment to the IHS

Caution:

To avoid the impact on the thermocouple during the SMT process, reflow must be performed before attaching the thermocouple to the grooved MCH IHS.

1. Clean the thermocouple wire groove with isopropyl alcohol (IPA) and a lint free cloth removing all residues prior to thermocouple attachment.
2. Place the thermocouple wire inside the groove letting the exposed wire and bead extend about 3.2 mm (0.125 inch) past the end of groove. Secure it with Kapton tape ([Figure 8](#)).
3. Lift the wire at the middle of groove with tweezers and bend the front of wire to place the thermocouple in the channel ensuring the tip is in contact with the end of the channel grooved in the IHS ([Figure 9](#)).
4. Place the MCH under the microscope unit (similar to the one used in [Figure 12](#)) to continue with process. It is also recommended to use a fixture to help holding the unit in place for the rest of the attach process.
5. Press the wire down about 6 mm (0.125 in.) from the thermocouple bead using the tweezers. Look in the microscope to perform this task. Place a piece of Kapton tape to hold the wire inside the groove ([Figure 11](#)). Refer to [Figure 10](#) for detailed bead placement.
6. Using the micromanipulator, place the needle near to the end of groove on top of thermocouple. Using the X, Y, and Z axes on the arm, place the tip of needle on top of the thermocouple bead. Press down until the bead is seated at the end of groove on top of the step (see [Figure 10](#) and [Figure 11](#)).
7. Measure resistance from thermocouple end wires (hold both wires to a DMM probe) to the IHS surface. This should be the same value as measured during the thermocouple conditioning see [Section 5.1.4](#), step 2 and [Figure 12](#).
8. Place a small amount of Loctite 498* adhesive in the groove where the bead is installed. Using a fine point device, spread the adhesive in the groove around the needle, the thermocouple bead and the thermocouple wires already installed in the groove during step 5. Be careful not to move the thermocouple bead during this step ([Figure 13](#)).

Figure 8. Securing Thermocouple Wires with Kapton Tape Prior to Attach

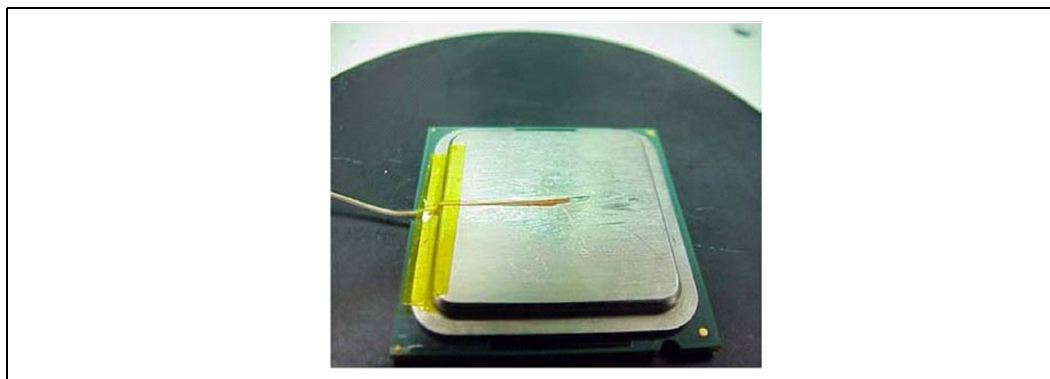


Figure 9. Thermocouple Bead Placement

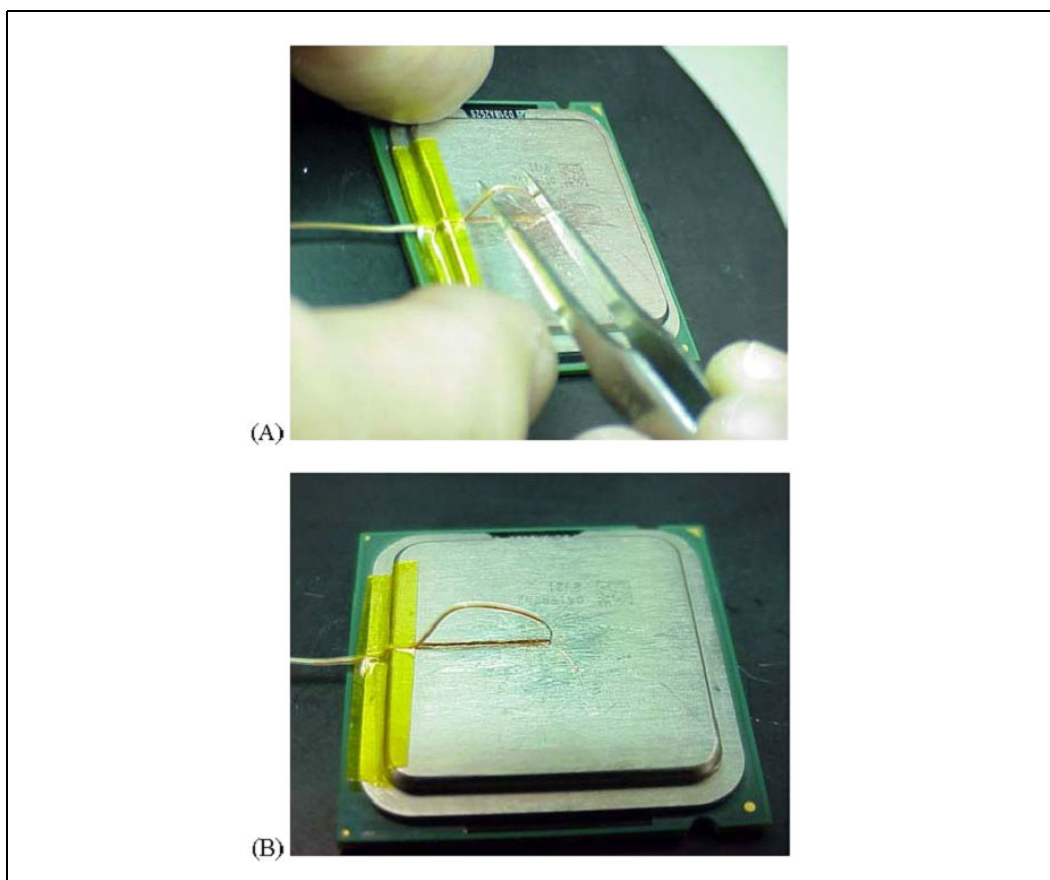


Figure 10. Position Bead on the Groove Step

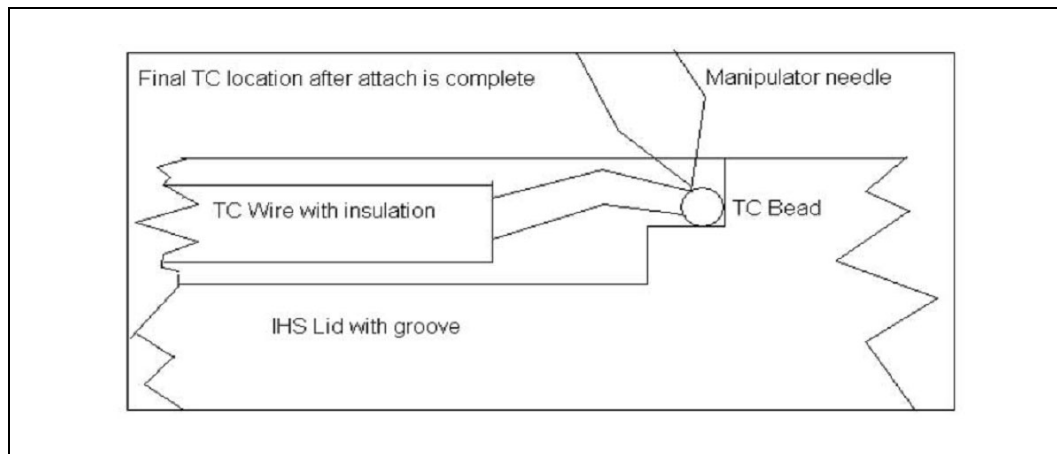


Figure 11. Using 3D Micromanipulator to Secure Bead Location

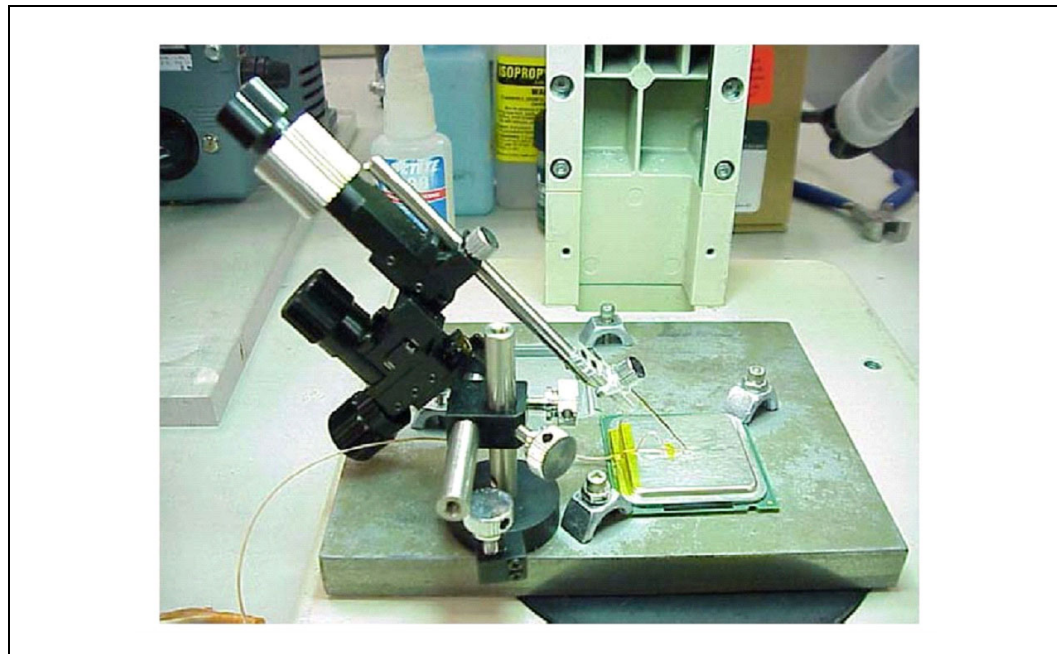


Figure 12. Measuring Resistance between Thermocouple and IHS



Figure 13. Applying the Adhesive on the Thermocouple Bead



5.1.6 Curing Process

1. Let the thermocouple attach sit in the open air for at least half an hour. Using any curing accelerator like Loctite 7452 Accelerator for this step is not recommended. Rapid contraction of the adhesive during curing may weaken bead attach on the IHS.
2. Reconfirm electrical connectivity with DMM before removing the micromanipulator (Figure 12) (see Section 5.1.4 step 2).
3. Remove the 3D Arm needle by holding down the MCH unit and lifting the arm.
4. Remove the Kapton tape, straighten the wire in the groove so it is flat all the way to the end of the groove (Figure 15)
5. Using a blade, shave excess adhesive above the IHS surface (Figure 15).

Note: Take usual precautions when using open blades.

6. Install new Kapton tape to hold the thermocouple wire down and fill the rest of groove with adhesive (See [Figure 16](#)). Make sure the wire and insulation is entirely within the groove and below the IHS surface.
7. Curing time for the rest of the adhesive in the groove can be reduced using Loctite 7452 Accelerator.
8. Repeat step 5 to remove any access adhesive to ensure flat IHS for proper mechanical contact to the heatsink surface.

5.1.7 Thermocouple Wire Management

Figure 14. Thermocouple Wire Management in the Groove



Figure 15. Removing Excess Adhesive from the IHS

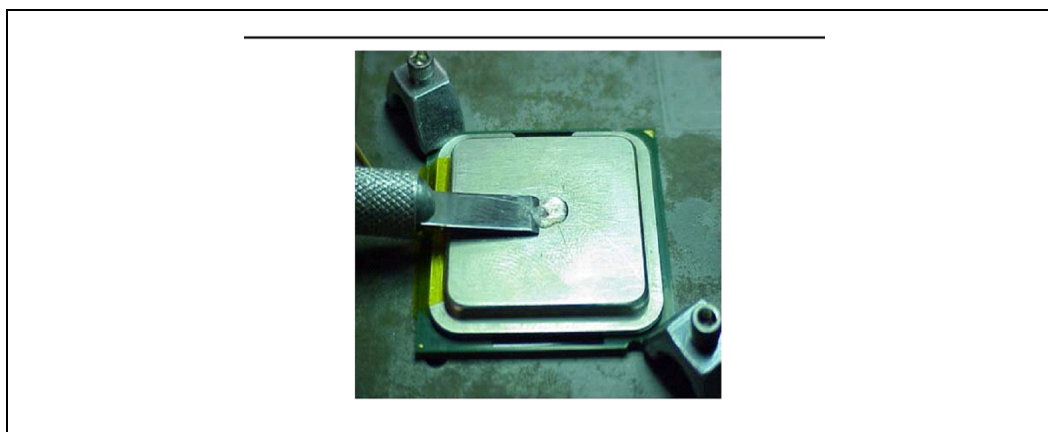
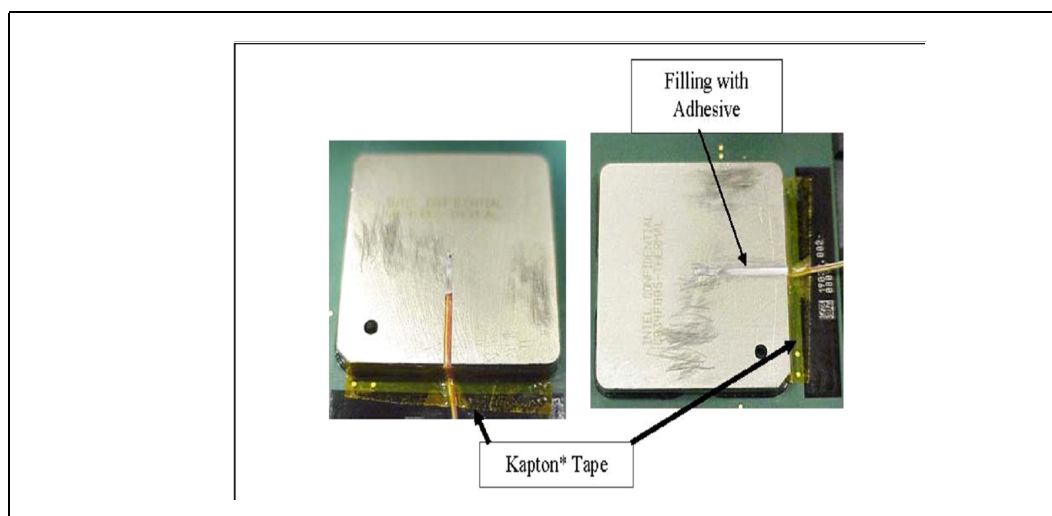




Figure 16. Filling the Groove with Adhesive



Note: Prior to installing the heatsink, be sure that the thermocouple wires remain below the IHS top surface by running a flat blade on top of the IHS for example.

5.2 Power Simulation Software

The power simulation software is a utility designed to dissipate the thermal design power on a Intel® 5000 Series Chipset MCH when used in conjunction with the Dual-Core Intel® Xeon® Processor 5100 Series Processor (1333 MHz). The combination of the above mentioned processor(s) and the higher bandwidth capability of the Intel 5000 Series Chipset enable higher levels of system performance. To assess the thermal performance of the chipset MCH thermal solution under “worst-case realistic application” conditions, Intel is developing a software utility that operates the chipset at near worst-case thermal power dissipation.

The power simulation software being developed should only be used to test thermal solutions at or near the thermal design power. Figure 5 shows a decision flowchart for determining thermal solution needs. Real world applications may exceed the thermal design power limit for transient time periods. For power supply current requirements under these transient conditions, please refer to each component's datasheet for the ICC (Max Power Supply Current) specification. Contact your Intel field sales representative to order the thermal models and user's guides.

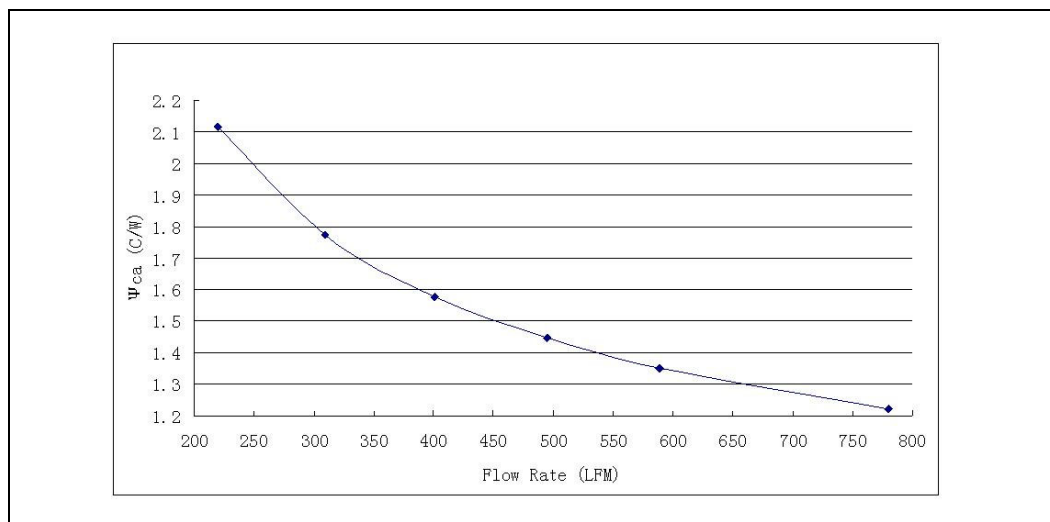
6.0 Reference Thermal Solution

Intel has developed one reference thermal solutions to meet the cooling needs of the Intel® 5000 Series Chipset MCH under the embedded operating environments and specifications defined in this document. This chapter describes the overall requirements for the torsional clip heatsink reference thermal solution including critical-to-function dimensions, operating environment, and validation criteria. Other chipset components may or may not need attached thermal solutions depending on your specific system local-ambient operating conditions. For information on the PXH/PXH-V, refer to thermal specification in the *Intel® 6700PXH 64-bit PCI Hub (PXH) Thermal/Mechanical Design Guidelines*. For information on Intel 631xESB/632xESB I/O Controller Hub, refer to thermal specification in the *Intel® 631xESB/632xESB I/O Controller Hub Thermal/Mechanical Design Guidelines*.

6.1 Thermal Performance

The AdvancedTCA* reference heatsink should be made from copper to achieve the necessary thermal performance. The minimum recommended airflow velocity through the cross section of the heatsink fins is 350 linear feet per minute (LFM). Based on the boundary conditions stated (external ambient temperature = 55 °C) the heatsink will meet the thermal performance needed to cool the chipset. Figure 17 depicts the measured thermal performance of the reference thermal solution versus approach air velocity. Since this data was measured at sea level, a correction factor would be required to estimate thermal performance at other altitudes.

Figure 17. Short Torsional Clip Heatsink Measured Thermal Performance versus Approach Velocity



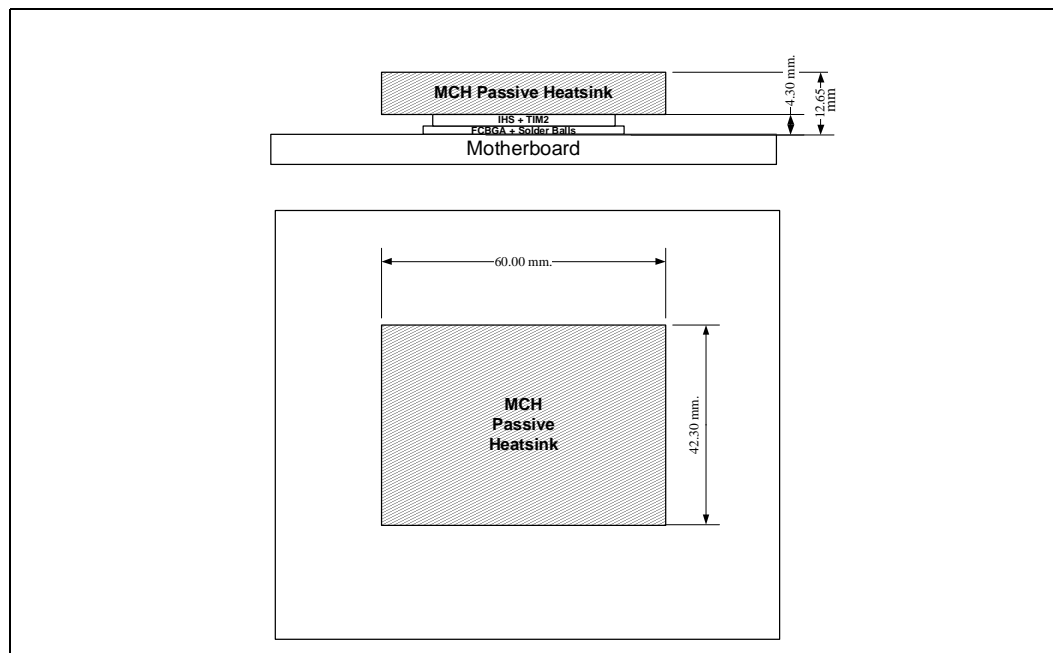


6.2 Mechanical Design Envelope

While each design may have unique mechanical volume and height restrictions or implementation requirements, the height, width, and depth constraints typically placed on the Intel® 5000 Series Chipset MCH thermal solution are shown in Figure 18.

When using heatsinks that extend beyond the chipset MCH reference heatsink envelope shown in Figure 18, any motherboard components placed between the heatsink and motherboard cannot exceed 2mm (0.07 in.) in height.

Figure 18. Short Torsional Clip Heatsink Volumetric Envelope for the Chipset MCH



6.3 Board-Level Components Keepout Dimensions

The location of hole patterns and keepout zones for the reference thermal solution are shown in Figure 19 and Figure 20. This reference thermal solution has the same hole patterns as that of the Intel® E7500 series chipset.

6.4 Torsional Clip Heatsink Thermal Solution Assembly

The reference thermal solution for the chipset MCH is a passive extruded heatsink with thermal interface. It is attached using a clip with each end hooked through an anchor soldered to the board. Figure 21 shows the reference thermal solution assembly and associated components. The torsional clip and the clip retention anchor are the same as the one used on the Intel® E7500 series chipset reference thermal solution.

Full mechanical drawings of the thermal solution assembly and the heatsink clip are provided in Appendix B, "Mechanical Drawings". Appendix A, "Thermal Solution Component Suppliers" contains vendor information for each thermal solution component.

Figure 19. Tall Torsional Clip Heatsink Board Component Keepout

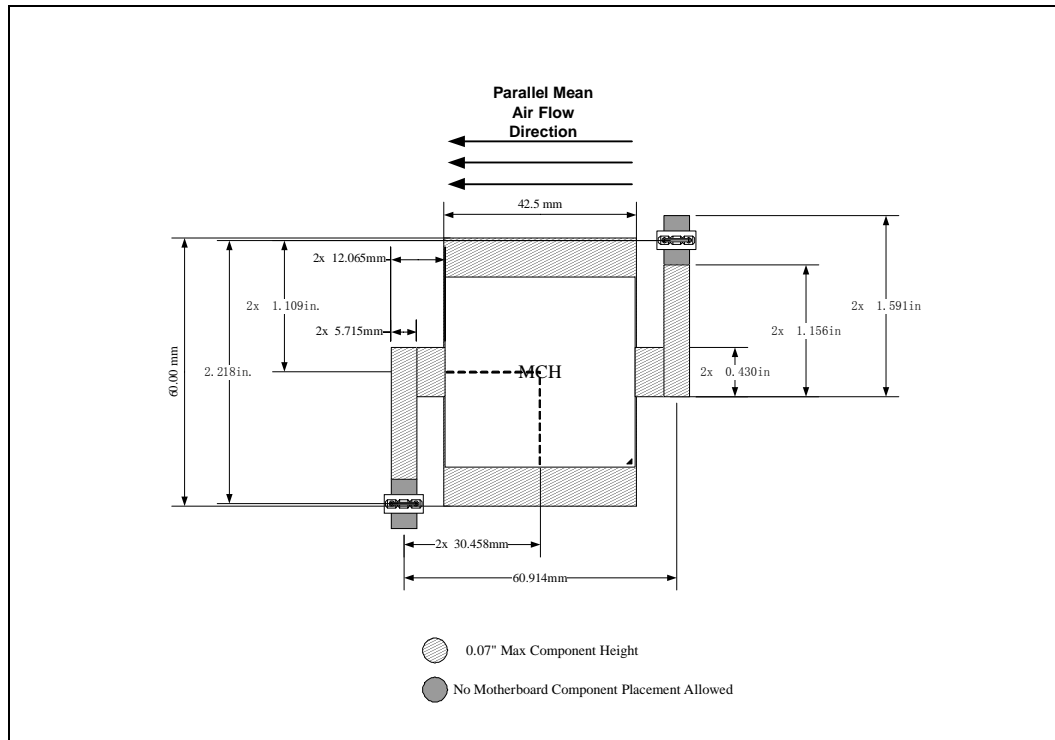
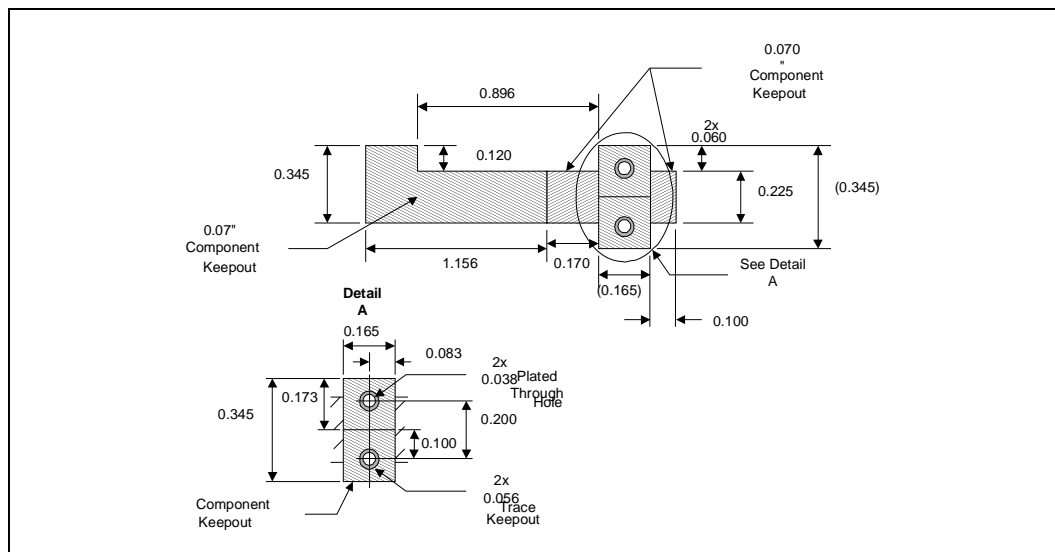


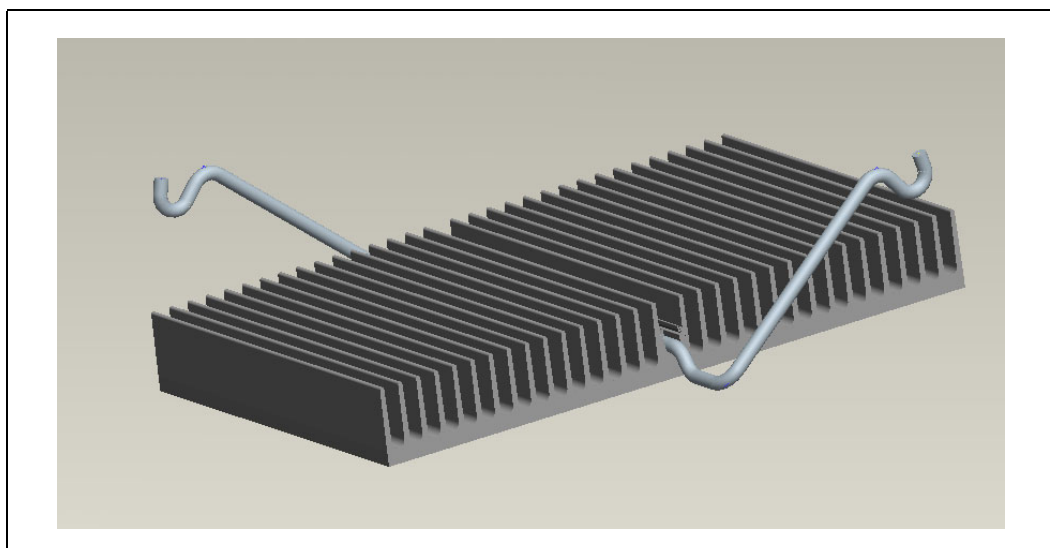
Figure 20. Retention Mechanism Component Keepout Zones



Note: All dimensions are in inches.

6.4.1 Heatsink Orientation

Since this solution is based on a unidirectional heatsink, mean airflow direction must be aligned with the direction of the heatsink fins.

**Figure 21. Tall Torsional Clip Heatsink Assembly**

6.4.2 Extruded Heatsink Profiles

The reference thermal solution uses an extruded heatsink for cooling the chipset MCH. [Figure 21](#) shows the heatsink profile. [Appendix A](#) lists a supplier for this extruded heatsink. Other heatsinks with similar dimensions and increased thermal performance may be available. Full mechanical drawing of this heatsink is provided in [Appendix B](#).

6.4.3 Mechanical Interface Material

There is no mechanical interface material associated with this reference solution.

6.4.4 Thermal Interface Material

A thermal interface material (TIM) provides improved conductivity between the IHS and heat sink. The reference thermal solution uses Honeywell PCM45 F, 0.25 mm (0.010 in.) thick, 25 mm x 25 mm (0.984 in. x 0.984 in.) square.

Note: Unflowed or "dry" Honeywell PCM45 F* has a material thickness of 0.010 inch. The flowed or "wet" Honeywell PCM45 F has a material thickness of ~0.003 inch after it reaches its phase change temperature.

6.4.4.1 Effect of Pressure on TIM Performance

As mechanical pressure increases on the TIM, the thermal resistance of the TIM decreases. This phenomenon is due to the decrease of the bond line thickness (BLT). BLT is the final settled thickness of the thermal interface material after installation of heatsink. The effect of pressure on the thermal resistance of the Honeywell PCM45 F TIM is shown in [Table 5](#).

Intel provides both End of Line and End of Life TIM thermal resistance values of Honeywell PCM45F. End of Line and End of Life TIM thermal resistance values are obtained through measurement on a Test Vehicle similar to Intel 5000 Series chipset's physical attributes using an extruded aluminum heatsink. The End of Line value represents the TIM performance post heatsink assembly while the End of Life value is



the predicted TIM performance when the product and TIM reaches the end of its life. The heatsink clip provides enough pressure for the TIM to achieve End of Line thermal resistance of 0.345°C inch²/W and End of Life thermal resistance of 0.459°C inch²/W.

Table 5. Honeywell PCM45 F* TIM Performance as a Function of Attach Pressure

Pressure (psi)	Thermal Resistance (°C × in ²)/W	
	End of Line	End of Life
2.18	0.391	0.551
4.35	0.345	0.459

6.4.5 Heatsink Clip

The reference solution uses a wire clip with hooked ends. The hooks attach to wire anchors to fasten the clip to the board. See [Appendix B, “Mechanical Drawings”](#) for a mechanical drawing of the clip.

6.4.6 Clip Retention Anchors

For Intel® 5000 series chipset-based platforms that have very limited board space, a clip retention anchor has been developed to minimize the impact of clip retention on the board. It is based on a standard three-pin jumper and is soldered to the board like any common through-hole header. A new anchor design is available with 45° bent leads to increase the anchor attach reliability over time. See [Appendix A](#) for the part number and supplier information.

6.5 Reliability Guidelines

Each motherboard, heatsink and attach combination may vary the mechanical loading of the component. Based on the end user environment, the user should define the appropriate reliability test criteria and carefully evaluate the completed assembly prior to use in high volume. Some general recommendations are shown in [Table 6](#).

Table 6. Reliability Guidelines

Test ⁽¹⁾	Requirement	Pass/Fail Criteria ⁽²⁾
Mechanical Shock	50 g, board level, 11 msec, 3 shocks/axis	Visual Check and Electrical Functional Test
Random Vibration	7.3 g, board level, 45 min/axis, 50 Hz to 2000 Hz	Visual Check and Electrical Functional Test
Temperature Life	85°C, 2000 hours total, checkpoints at 168, 500, 1000, and 2000 hours	Visual Check
Thermal Cycling	–5°C to +70°C, 500 cycles	Visual Check
Humidity	85% relative humidity, 55°C, 1000 hours	Visual Check

Note: It is recommended that the above tests be performed on a sample size of at least twelve assemblies from three lots of material.

Additional pass/fail criteria may be added at the discretion of the user.



Appendix A Thermal Solution Component Suppliers

A.1 Torsional Clip Heatsink Thermal Solution

Part	Intel Part Number	Supplier (Part Number)	Contact Information
Heatsink Assembly includes: • Unidirectional Fin Heatsink • Thermal Interface Material • Torsional Clip	D12405-001	CCI/ACK	Harry Lin (USA) 714-739-5797 hlinack@aol.com Monica Chih (Taiwan) 866-2-29952666, x131 monica_chih@ccic.com.tw
Undirectional Fin Heatsink (42.50 x 60 x 8.9 mm)	D12404-001	CCI/ACK	Harry Lin (USA) 714-739-5797 hlinack@aol.com Monica Chih (Taiwan) 866-2-29952666, x131 monica_chih@ccic.com.tw
Thermal Interface (PCM45F)	C34795-001	Honeywell PCM45F	Scott Miller 509-252-2206 scott.miller4@honeywell.com
Heatsink Attach Clip	D10234-001	CCI/ACK	Harry Lin (USA) 714-739-5797 hlinack@aol.com Monica Chih (Taiwan) 866-2-29952666, x131 monica_chih@ccic.com.tw
		Foxconn	Bob Hall (USA) 503-693-3509, x235 bhall@foxconn.com
Solder-Down Anchor	A13494-005	Foxconn (HB96030-DW)	Julia Jiang (USA) 408-919-6178 juliaj@foxconn.com

Note: The enabled components may not be currently available from all suppliers. Contact the supplier directly to verify time of component availability.



Appendix B Mechanical Drawings

Table B-1 lists the mechanical drawings included in this appendix.

Table 7. Mechanical Drawing List

Drawing Description	Figure Number
Short Torsional Clip Heatsink Assembly Drawing y	Figure 22
Short Torsional Clip Heatsink Drawing(Sheet 1 of 2)	Figure 23
Short Torsional Clip Heatsink Drawing(Sheet 2 of 2)	Figure 23
Short Torsional Clip Heatsink Clip Drawing	Figure 24
Tall Torsional Clip Heatsink Clip Drawing	Figure 25

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SCALE 2

SCALE 2

SCALE 2

SCALE 2

NOTES:

1. CLIP MUST STAY ATTACHED TO HEAT SINK
2. CLIP SHOULD BE ABLE TO ROTATE 360 DEGREES AFTER CRIMPING PROCESS.

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

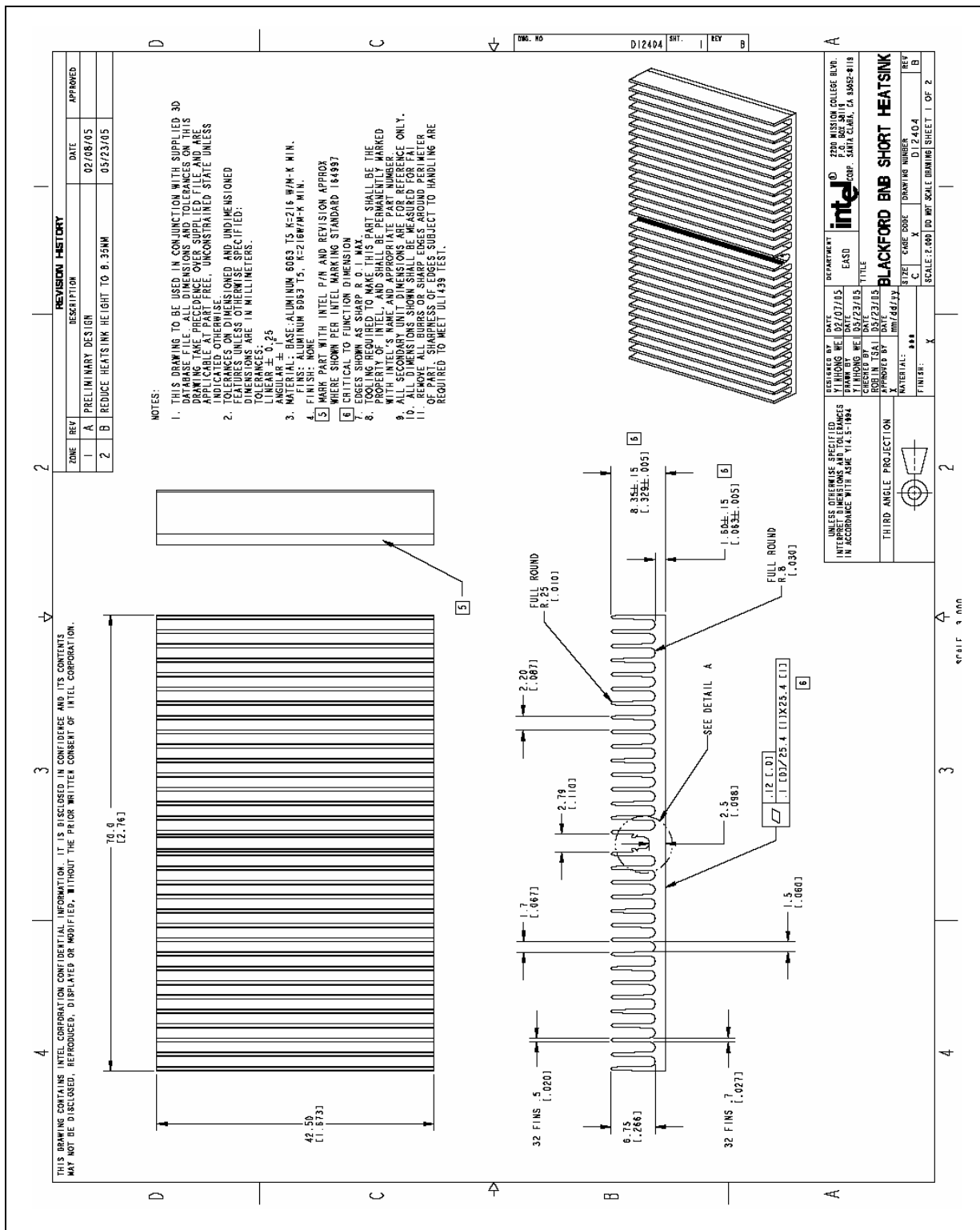
ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.4MM X 25.4MM	07/09/15	
1	A	DRAWING INITIAL RELEASED	02/08/15	X

SCALE 2

REVISION HISTORY

ZONE	REV	DESCRIPTION	DATE	APPROVED
2	B	INCREASED TIM SURFACE SIZE TO 25.		

Figure 23. Short Torsional Clip Heatsink Drawing



September 2006

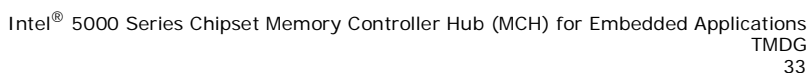




Figure 25. Tall Torsional Clip Heatsink Clip Drawing

